

## PRODUCT / PROCESS CHANGE NOTIFICATION

### 1. PCN basic data

1.1 Company	 STMicroelectronics International N.V
1.2 PCN No.	MDG/23/14327
1.3 Title of PCN	STM32H562xGx & STM32H563xGx - FLASH memory configuration fixed on 1MB listed products
1.4 Product Category	STM32H562xGx, STM32H563xGx
1.5 Issue date	2023-12-06

### 2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Ricardo Antonio DE SA EARP
2.2.2 Marketing Manager	Veronique BARLATIER
2.2.3 Quality Manager	Pascal NARCHE

### 3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
General (Test Program)	Pattern modification : test pattern without reliability impact not supplied or agreed by customer	ST Crolles 300 (France)

### 4. Description of change

	Old	New
4.1 Description	STM32H562xG / STM32H563xG - (Die484 - cut1.3 revision X) products shows regression with 1MByte flash memory only a. Incorrect flash memory configuration on early STM32H562xG and STM32H563xG devices b. Bootloader (BL) V14.4 EEPROM sector erase is not working - Limitation is described in AN2606. c. System FLASH Security Package (SFSP) V2.5.0 - has limitations.	STM32H562xG / STM32H563xG - (Die484 - cut1.3 revision X) product with 1MByte flash memory is fixed as below: a. Incorrect flash memory configuration on early STM32H562xG and STM32H563xG devices is fixed - refer to ES0565 Rev4 Nov2023. b. Bootloader (BL) V14.5 EEPROM sector erase is fixed- refer to latest AN2606. c. System FLASH Security Package (SFSP) V2.6.0 limitation is now fixed - refer to AN6014 Rev1 - October 2023.
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	Functionality enhancement	

### 5. Reason / motivation for change

5.1 Motivation	Improvements was implemented to increase robustness, performances and quality of our products.
5.2 Customer Benefit	SERVICE IMPROVEMENT

### 6. Marking of parts / traceability of change

6.1 Description	Traceability ensured by ST internal tools. Customer can detect the change by reading the new version of SFSP version 2.6.0 and new BL version 14.5 as indicated in additional document.
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### 7. Timing / schedule

7.1 Date of qualification results	2023-10-24
7.2 Intended start of delivery	2023-11-22
7.3 Qualification sample available?	Upon Request

**8. Qualification / Validation**

<b>8.1 Description</b>	14327 PCI14327_Sanity Check.pdf		
<b>8.2 Qualification report and qualification results</b>	Available (see attachment)	<b>Issue Date</b>	2023-12-06

**9. Attachments (additional documentations)**

14327 Public product.pdf  
14327 PCI14327\_Sanity Check.pdf  
14327 PCN14327\_Additional information.pdf

**10. Affected parts**

<b>10. 1 Current</b>		<b>10.2 New (if applicable)</b>
<b>10.1.1 Customer Part No</b>	<b>10.1.2 Supplier Part No</b>	<b>10.1.2 Supplier Part No</b>
	STM32H562RG-T6	

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**STM32H562xG & STM32H563xG - FLASH memory configuration  
fixed on 1MB listed products.**

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**MDG – General Purpose Microcontrollers Division (GPM)**

**Material under test**

The number of units being tested in table below.

<b><i>Samples configs and shipment</i></b>	<b><i>GNB</i></b>	<b><i>Le Mans</i></b>	<b><i>Tunis</i></b>
<b><i>STM32H563ZGT6 1MB - LQ144 No Crypto</i></b>	<b><i>2 samples</i></b>	<b><i>2 samples</i></b>	<b><i>2 samples</i></b>
<b><i>STM32H563ZIT6 2MB - LQ144 No Crypto</i></b>	<b><i>2 samples</i></b>	<b><i>2 samples</i></b>	<b><i>2 samples</i></b>

BL(v14.5)/SFSP(v2.6.0) versions tested on above samples

- Debug Authentication tested on sales type 1M - passed/ OK
- Erase EEPROM sectors by BL tested on sales type 1M passed/ OK

**Conclusion:**

All verification tests on BL (BootLoader) and SFSP (Scalable Firmware Support Package) on newly programmed parts are successful.



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## PRODUCT/PROCESS CHANGE NOTIFICATION

### PCN14327 – Additional Information

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### **STM32H562xGx & STM32H563xGx - FLASH memory configuration fixed on 1MB listed products.**

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#### **MDG – General Purpose Microcontrollers Division (GPM)**

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##### **What are the changes?**

1-Mbyte part numbers (STM32H562xG and STM32H563xG with a date code earlier than week 35 2023) are not correctly configured to support the two 512-Kbyte flash memory banks. Instead, the flash memory configuration is set to 2 Mbytes (two 1-Mbyte banks). The incorrect configuration can be identified by reading the bootloader version (at address 0x0BF9 FAFE): it returns the value 0xE4 (2-Mbyte configuration), while it is 0xE5 for the correctly configured part numbers. Bootloader (BL) and System FLASH Security Package (SFSP) have changed due to Debug Authentication (DA) issue on 1MB products.

##### **Documents to refer to are listed below:**

- Incorrect flash memory configuration on early STM32H562xG and STM32H563xG devices is fixed – Refer to **ES0565 Rev4 Nov2023**.
- Bootloader (BL) V14.5 EEPROM sector erase is fixed. Refer to latest **AN2606**.
- System FLASH Security Package (SFSP) V2.6.0 limitation is now fixed. Refer to **AN6014 Rev1 - October 2023**.

Only a few Finished Goods (FG) have been codified with wrong settings (see table below).

- The customer can detect the change by reading the new version of SFSP version 2.6.0 (0x02060000) from address “0x0BF960CC” and new BL version 14.5 (0xE5) from address ‘0x0BF9FAFE’

**Table describing the changes:**

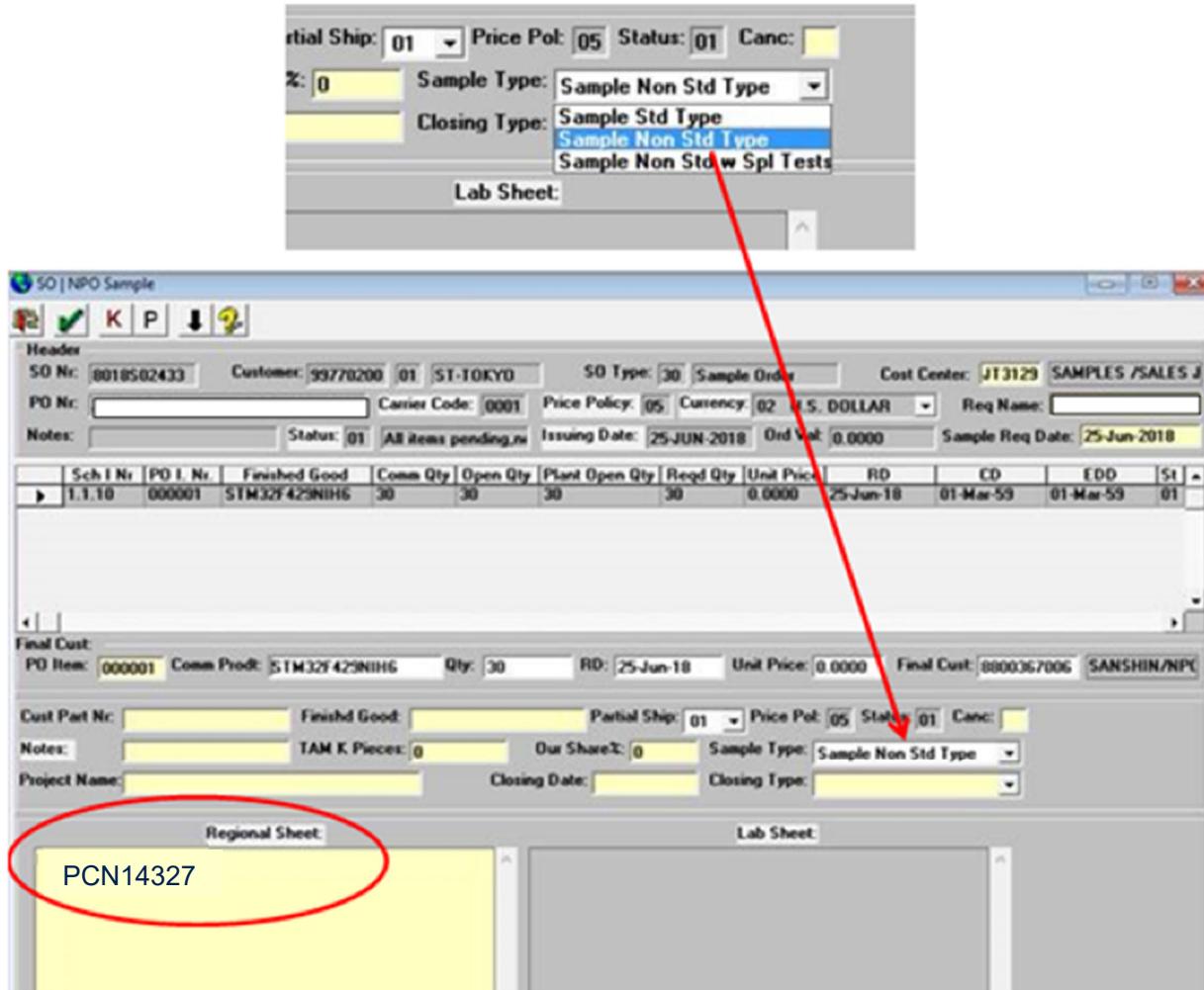
		Current condition	New condition
Package	Commercial Product	Old Finished Good (FG) (BL) V14.4/ (SFSP) V2.5.0	New Finished Good (FG) (BL) V14.5/ (SFSP) V2.6.0
UFBGA 7X7 169L	<b>STM32H562AGI6</b>	32H562AGI6\$24	32H562AGI6 <u>K\$24</u>
LQFP 64 10x10	<b>STM32H562RGT6</b>	32H562RGT6\$74	32H562RGT6 <u>K\$74</u>
	<b>STM32H562RGT6TR</b>	32H562RGT6TR\$74	32H562RGT6TR <u>K\$74</u>
	<b>STM32H563RGT6</b>	32H563RGT6\$74	32H563RGT6 <u>K\$74</u>
LQFP 100 14x14	<b>STM32H562VGT6</b>	32H562VGT6\$E4	32H562VGT6 <u>K\$E4</u>
	<b>STM32H563VGT6</b>	32H563VGT6\$E4	32H563VGT6 <u>K\$E4</u>

No marking change on top of the package.

## How to order samples

For all samples request linked to this PCN, please:

- place a Non-standard sample order (choose Sample Non Std Type from pull down menu)
- insert the PCN number “**PCN14327**” into the NPO Electronic Sheet/Regional Sheet
- request sample(s) through Notice tool, indicating a single Commercial Product for each request



SO | NPO Sample

Header

SO Nr: 8018502433 Customer: 33770200 01 ST-TOKYO SO Type: 30 Sample Order Cost Center: JT3129 SAMPLES /SALES J

PO Nr: Carrier Code: 0001 Price Policy: 05 Currency: 02 U.S. DOLLAR Req Name:

Notes: Status: 01 All items pending.nw Issuing Date: 25-JUN-2018 Ord Val: 0.0000 Sample Req Date: 25-Jun-2018

Sch I Nr	PO I. Nr.	Finished Good	Comm Qty	Open Qty	Plant Open Qty	Reqd Qty	Unit Price	RD	CD	EDD	St
1.1.10	000001	STM32F429NIH6	30	30	30	30	0.0000	25-Jun-18	01-Mar-59	01-Mar-59	01

Final Cust:

PO Item: 000001 Comm Prod: STM32F429NIH6 Qty: 30 RD: 25-Jun-18 Unit Price: 0.0000 Final Cust: 88000367006 SANSHIN/NPC

Cust Part Nr: Finished Good: Partial Ship: 01 Price Pol: 05 Status: 01 Canc:

Notes: TAM K Pieces: 0 Our Share: 0 Sample Type: Sample Non Std Type

Project Name: Closing Date: Closing Type:

Regional Sheet: Lab Sheet:

PCN14327



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## Public Products List

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**PCN Title :** STM32H562xGx & STM32H563xGx - FLASH memory configuration fixed on 1MB listed products

**PCN Reference :** MDG/23/14327

**Subject :** Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

STM32H562RGT6	STM32H562RGT6TR	STM32H563RGT6
STM32H563VGT6	STM32H562VGT6	STM32H562AGI6

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